Attachment no. 1

**DESCRIPTION OF THE SUBJECT OF THE ORDER**

1. **Subject of the order**

The subject of the order is a supply of semiconductor wafers, listed below by denomination and quantity needed:

* GaAs 3” 100 pcs.

1. **Scope of the subject of the order**

Detailed description of the subject of the order is contained in item 5.

1. **Criteria**

Offers will be evaluated according to point scale with maximum number of points amounting to 100.

|  |  |  |
| --- | --- | --- |
| Criterion | Maximum number of points S | Points granting method |
| Net price (P) | 100 | S x Pmin/Pi |

Where:

* Pi – net price of the goods – for submitted offer
* Pmin – minimal net price of the goods among all submitted offers
* S – number of points

Final score will be calculated by summarizing component parts, and then rounding up to two decimal places (rounding from “5” up).

1. **Completion deadline**

**Time of performance: 8 weeks from the date of placing the order.**

1. **Parameters**
   1. **Detailed scope of the subject of the order**

|  |  |  |  |
| --- | --- | --- | --- |
| Name | | Parameter | Specification |
| **GaAs** | Diameter 3”  Thickness: 1.1 mm | Grade: | Prime, Epi-ready |
| Growth method | VGF |
| Conductivity type | Semi-insulating |
| Doping | Undoped |
| Orientation | (100)±0.2o |
| Primary flat | EJ (0-1-1) |
| Secondary flat | EJ (0-11) |
| Resistivity | min. 1E8 Ω/cm |
| EPD (average): | <5000/cm2 |
| Mobility | min: 4870 max: 6050 cm^2/V\*cm |
| Surface finish | Both sides polished  (1 surface EPI ready  2 surface polished) |
| Packaging: | ePAK |